

P-Channel Enhancement Mode Power MOSFET

Description

The PTIIIF uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

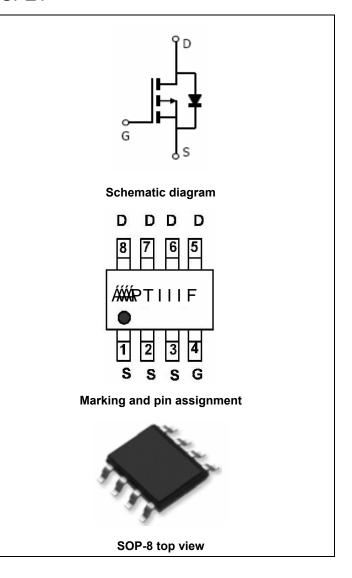
General Features

• V_{DS} =-55V, I_{D} =-5A $R_{DS(ON)}$ <80m Ω @ V_{GS} =-10V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- DC-DC Converter



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
PTIIIF	PTIIIF	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

The country manner than go (14 to common country)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	-55	V		
Gate-Source Voltage	V _{GS}	±20	V		
Drain Current-Continuous	I _D	-5	Α		
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	-3.0	Α		
Pulsed Drain Current	I _{DM}	-25	А		
Maximum Power Dissipation	P _D	3	W		
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	$^{\circ}\! \mathbb{C}$		





Thermal Characteristic

Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA -5		-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-55V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V		-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=-250\mu A$	-1.5	-2.6	-3.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-5A	-	64	80	mΩ
Forward Transconductance	g FS	V _{DS} =-15V,I _D =-5A	16	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ - 20\/\/ -0\/	-	1450	-	PF
Output Capacitance	Coss	V_{DS} =-20V, V_{GS} =0V, F=1.0MHz	-	145	-	PF
Reverse Transfer Capacitance	C _{rss}	r=1.0WHZ	-	110	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	8	-	nS
Turn-on Rise Time	t _r	V_{DD} =-30V, , R_L =30 Ω	-	9	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =-10 V , R_{GEN} =6 Ω	-	65	-	nS
Turn-Off Fall Time	t _f		-	30	-	nS
Total Gate Charge	Qg	\/ - 20\/ - 54	-	26	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =-30V, I_{D} =-5A, V_{GS} =-10V	-	4.5	-	nC
Gate-Drain Charge	Q_{gd}	v _{GS} 10v	-	7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-3A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	-5	Α

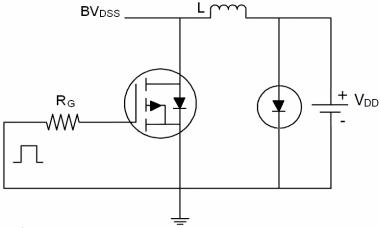
Notes:

- $\textbf{1.} \ \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

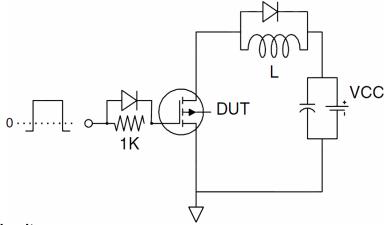


Test Circuit

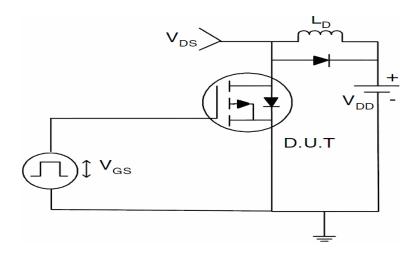
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

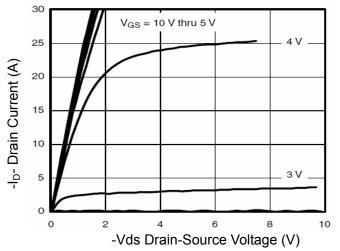


Figure 1 Output Characteristics

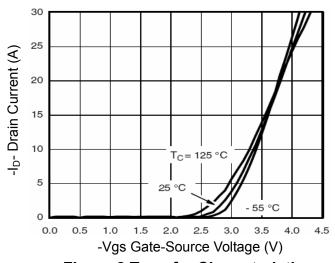


Figure 2 Transfer Characteristics

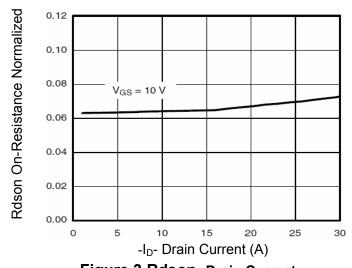


Figure 3 Rdson- Drain Current

(Curves)

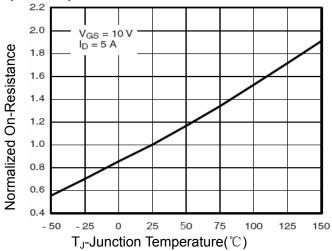


Figure 4 Rdson-Junction Temperature

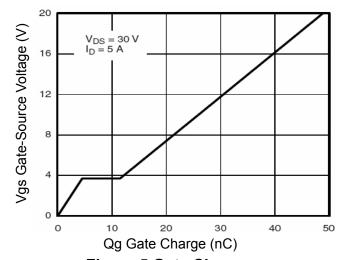


Figure 5 Gate Charge

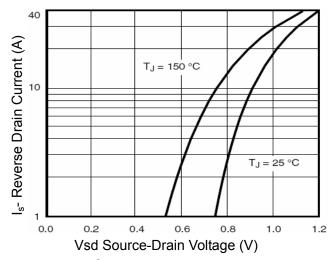


Figure 6 Source- Drain Diode Forward

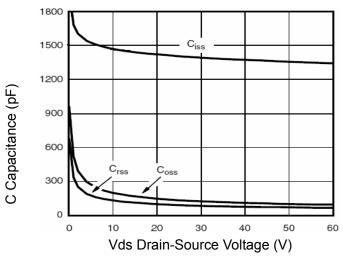


Figure 7 Capacitance vs Vds

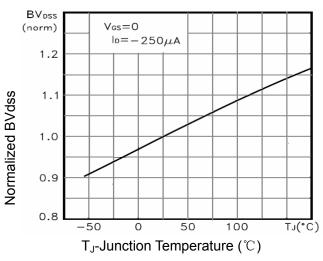


Figure 9 BV_{DSS} vs Junction Temperature

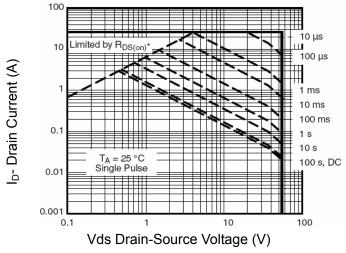


Figure 8 Safe Operation Area

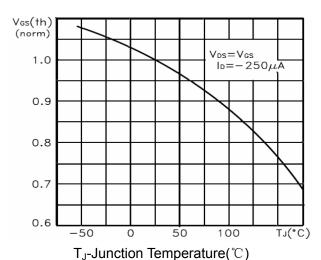


Figure 10 V_{GS(th)} vs Junction Temperature

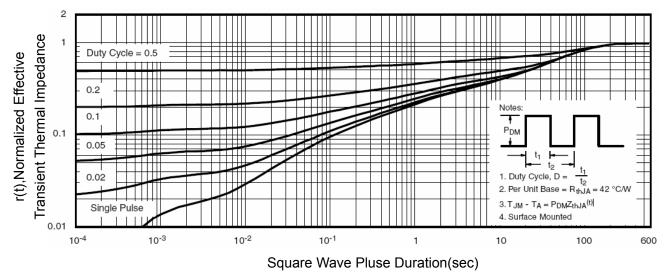
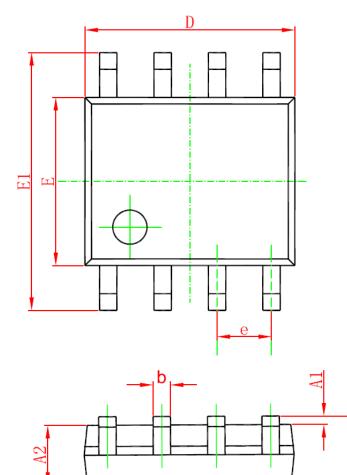
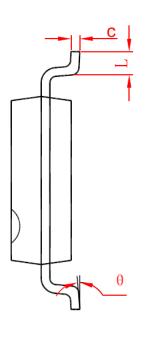


Figure 11 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information





Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1. 350	1. 750	0. 053	0. 069	
A1	0. 100	0. 250	0.004	0. 010	
A2	1. 350	1. 550	0.053	0. 061	
b	0. 330	0. 510	0. 013	0. 020	
С	0. 170	0. 250	0.006	0. 010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3. 800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270 (BSC)		0. 050 (BSC)		
L	0. 400	1. 270	0. 016	0. 050	
θ	0°	8°	0°	8°	



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